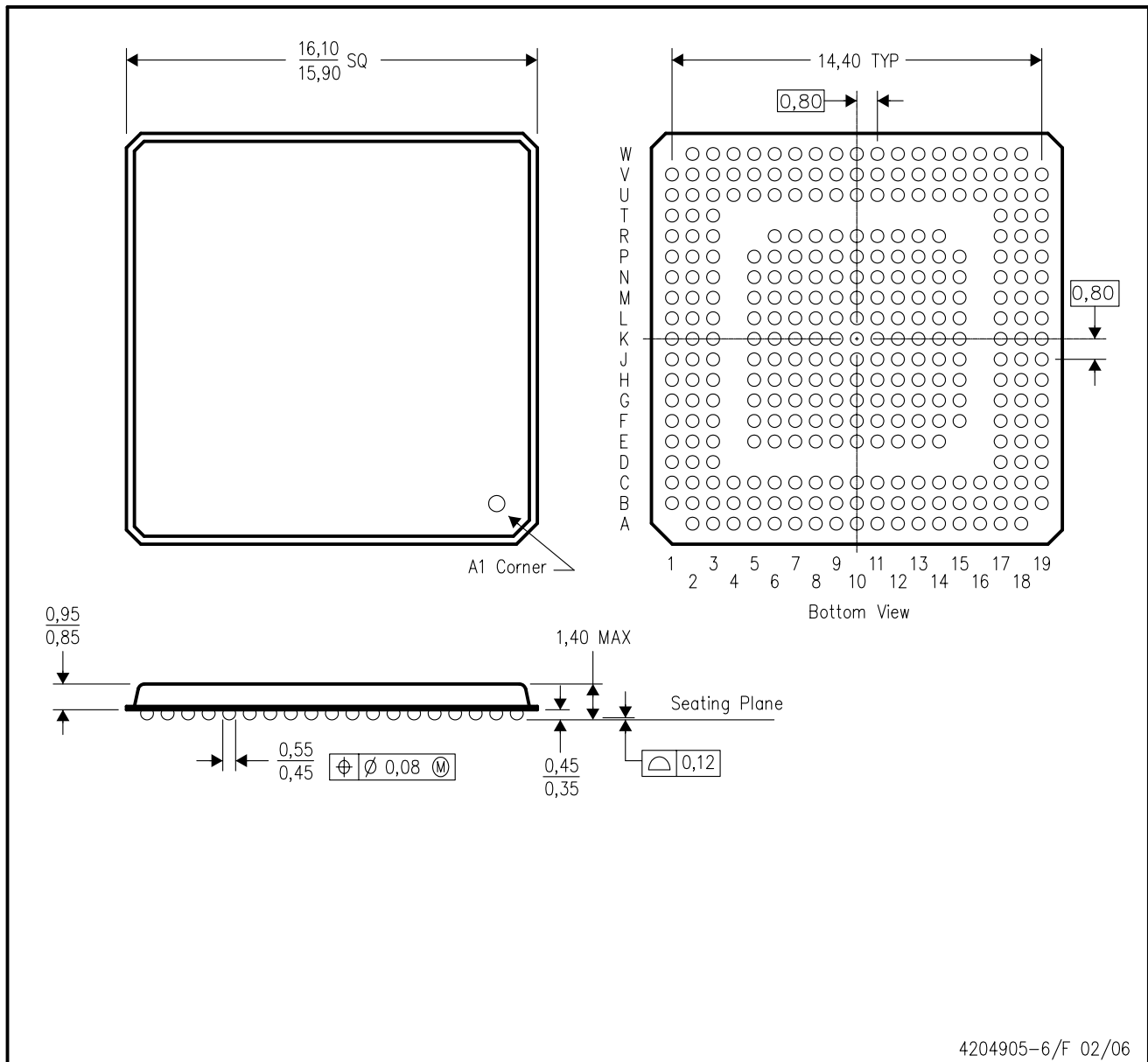


ZHK (S-PBGA-N306)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. This is a lead-free solder ball design.
 - D. Maximum height of 1.4mm considers material tolerance only. Allowable variance of + 0.1mm for warpage.

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